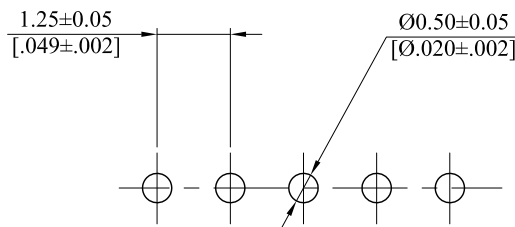
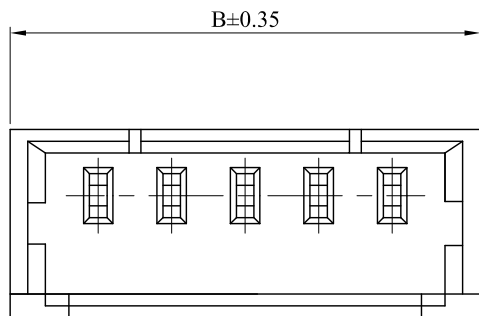


RoHS COMPLIANT

CUSTOMER DRAWING			
REV.	ECO. NO.	DESCRIPTION	DATE
B	ES090711	Upgrade drawing frame	2009.07.11
C	ES170924	Update the drawing	2017.08.18



Recommended PCB Layout

Note:
 Material:
 Insulator: High Temperature Thermoplastic, UL94 V-0, Natural
 Contact: Copper Alloy

General Part Number:

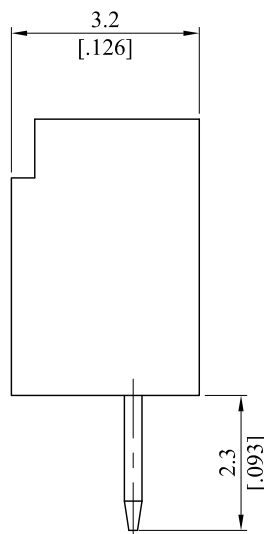
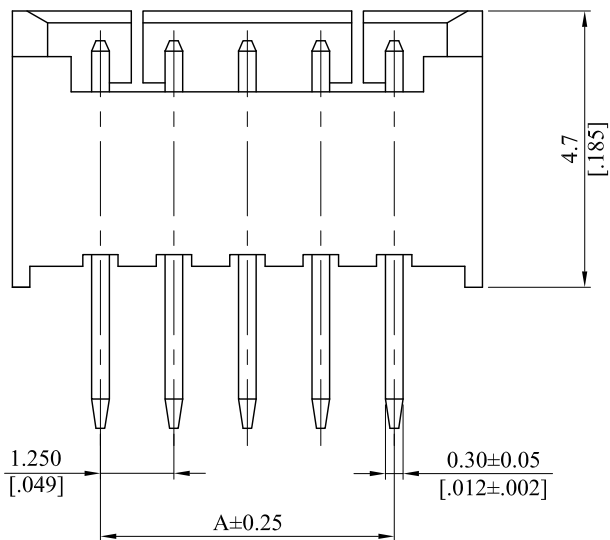
1254P ** V * 00
 1 2

1. No.of circuits(02~15)

2. Plating:

- O=Matte Tin plated 80µ"min.over 30µ"min.Nickel underplating overall
- F=Selective Gold flash on contact area over 30µ"min.Nickel underplating overall, Tin plated on solder tails
- J= 15µ"min.Selective Gold on contact area over 30µ"min.Nickel underplating overall, Tin plated on solder tails
- K=30µ"min.Selective Gold on contact area over 30µ"min.Nickel underplating overall, Tin plated on solder tails

A=1.25mm(.049")*No.of spaces
 B=A+6.00mm(.236")
 C=A+3.00mm(.118")



TOLERANCE UNLESS OTHERWISE SPECIFIED			LEOCO CORPORATION <i>http://www.leoco.com.tw</i>		
mm	mm	inch	APPROVED BY:	DATE:	TITLE:
[inch]			Chard	2017.08.18	1.25mm(.049") Pitch Wafer
1 PLACE	± 0.30	± ---	CHECKED BY:	DATE:	
2 PLACES	± 0.20	± .012	Angel	2017.08.18	PART NO.: 1254P**V*00
3 PLACES	± 0.10	± .008	DRAWN BY:	DATE:	
4 PLACES	± ---	± .004	Brian	2017.08.18	DRAWING NO.: 125409S
ANGULAR ±1°			SIZE:	SCALE:	
			A3	1:1	C
			SHEET: 1 OF 1		